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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10020636	FILING DATE 12/14/2001	CLASS 257	SUBCLASS 243	GAU 2811	EXAMINER 1027 M. Ichikawa
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\*\*APPLICANTS: Ma Bodan; Hong Sun; Tong Quinn;

\*\*CONTINUING DATA VERIFIED:

\*\* FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 1979.EEM
Verified and Acknowledged Examiner's initials			
TITLE : Dual cure B-stageable underfill for wafer level			
U.S. DEPT. OF COMMERCE/PAT & TM-PTO-436L (Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims Print Claim for O.G	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.
TERMINAL DISCLAIMER		Print Fig. <input checked="" type="checkbox"/>	
PREPARED FOR ISSUE		Application Examiner	
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